

1000V N-Channel MOSFET

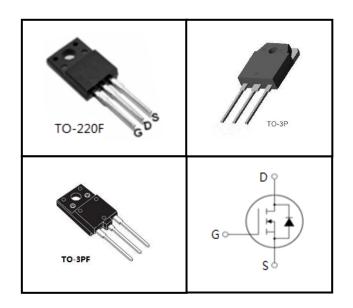
FEATURES

- Fast switching
- 100% avalanche tested
- Improved dv/dt capability

APPLICATIONS

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)

Device Marking and Package Information					
Device	Package	Marking			
CS4N100F	TO-220F	CS4N100F			
CS4N100V	TO-3P	CS4N100V			
CS4N100VF	TO-3PF	CS4N100VF			



Absolute Maximum Ratings $T_C = 25^{\circ}C$, unless otherwise noted					
Parameter	Symbol	Value			l locit
raidinetei		TO-220F	TO-3P	TO-3PF	Unit
Drain-Source Voltage (V _{GS} = 0V)	V _{DSS}	1000			V
Continuous Drain Current	I _D	4		Α	
Pulsed Drain Current (note1)	I _{DM}	16		Α	
Gate-Source Voltage	V _{GSS}	±30		٧	
Single Pulse Avalanche Energy (note2)	E _{AS}	88		mJ	
Avalanche Current (note1)	I _{AS}	4.2		Α	
Repetitive Avalanche Energy (note1)	E _{AR}	52		mJ	
Power Dissipation (T _C = 25°C)	P_{D}	36 75		W	
Operating Junction and Storage Temperature Range	T _J , T _{stg}	-55~+150			°C

Thermal Resistance					
Baramatar	Symbol	Value			11
Parameter		TO-220F	TO-3P	TO-3PF	Unit
Thermal Resistance, Junction-to-Case	R _{thJC}	3.47	1.67		00/14/
Thermal Resistance, Junction-to-Ambient	R _{thJA}	62.5	60		°C/W

CS4N100F,CS4N100V,CS4N100VF

Specifications $T_J = 25^{\circ}$ C, unless otherwise noted							
Doromotor	Symbol	Test Conditions	Value			11.24	
Parameter	Эушрог	rest Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	1000			V	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 1000V, V_{GS} = 0V, T_{J} = 25^{\circ}C$	ŀ		1	μΑ	
Gate-Source Leakage	I _{GSS}	$V_{GS} = \pm 30V$			±100	nA	
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	3.0		4.0	V	
Drain-Source On-Resistance (Note3)	R _{DS(on)}	$V_{GS} = 10V, I_D = 2.0A$		3.6	4.3	Ω	
Dynamic							
Input Capacitance	C _{iss}	V - 0V		689			
Output Capacitance	C _{oss}	$V_{GS} = 0V,$ $V_{DS} = 25V,$		68		pF	
Reverse Transfer Capacitance	C _{rss}	f = 1.0MHz		13			
Total Gate Charge	Q_g			27		nC	
Gate-Source Charge	Q_{gs}	$V_{DD} = 800V, I_{D} = 4.0A, V_{GS} = 10V$		4			
Gate-Drain Charge	Q_{gd}	93		12			
Turn-on Delay Time	t _{d(on)}			37			
Turn-on Rise Time	t _r	$V_{DD} = 500V, I_{D} = 4.0A,$		16			
Turn-off Delay Time	t _{d(off)}	$R_G = 25 \Omega$		145		ns	
Turn-off Fall Time	t _f			37			
Drain-Source Body Diode Character	Drain-Source Body Diode Characteristics						
Continuous Body Diode Current	Is	T 05.00			4	^	
Pulsed Diode Forward Current	I _{SM}	T _C = 25 °C			16	Α	
Body Diode Voltage	V _{SD}	$T_J = 25^{\circ}\text{C}, I_{SD} = 2.0\text{A}, V_{GS} = 0\text{V}$			1.4	V	
Reverse Recovery Time	t _{rr}	$V_{GS} = 0V, I_{S} = 4.0A,$		980		ns	
Reverse Recovery Charge	Q _{rr}	di _F /dt =100A /µs		1.6		μC	

Notes

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature
- 2. L = 10.0mH, V_{DD} = 50V, R_G = 25 Ω , Starting T_J = 25 $^{\circ}C$
- 3. Pulse Test: Pulse width ≤ 300µs, Duty Cycle ≤ 1%



Typical Characteristics $T_J = 25^{\circ}C$, unless otherwise noted

Figure 1. Output Characteristics (T_J = 25°C)

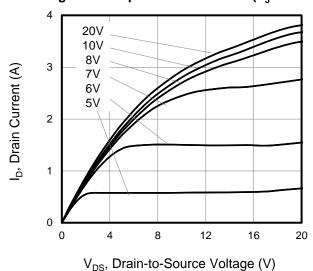


Figure 3. Drain Current vs. Temperature

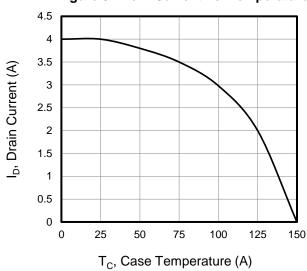


Figure 5. Transfer Characteristics

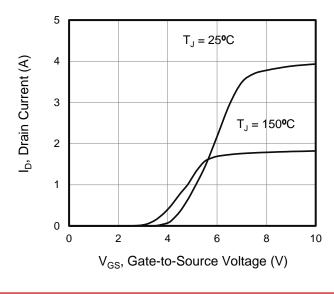


Figure 2. Body Diode Forward Voltage

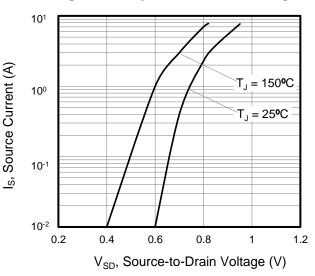
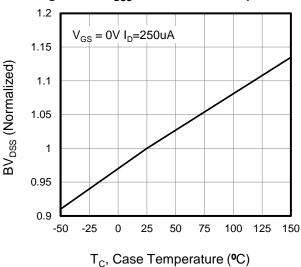
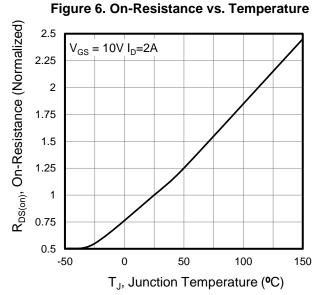


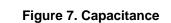
Figure 4. BV_{DSS} Variation vs. Temperature





CS4N100F,CS4N100V,CS4N100VF

Typical Characteristics $T_J = 25^{\circ}C$, unless otherwise noted



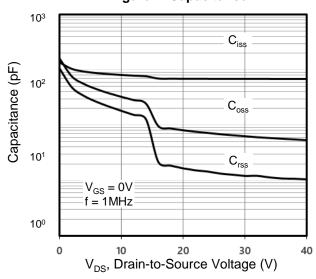


Figure 8. Gate Charge

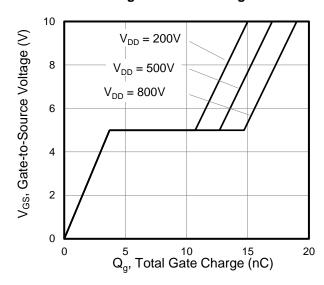


Figure 9. Transient Thermal Impedance TO-220F

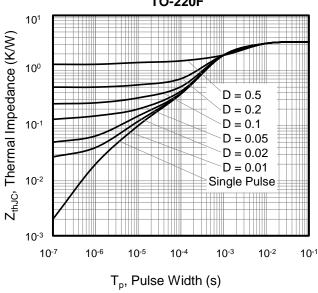


Figure 10. Transient Thermal Impedance TO-3P,TO-3PF

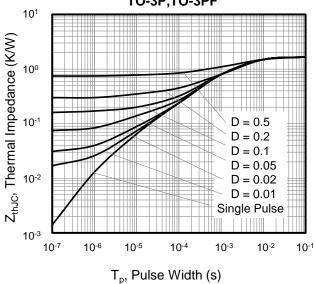


Figure A: Gate Charge Test Circuit and Waveform

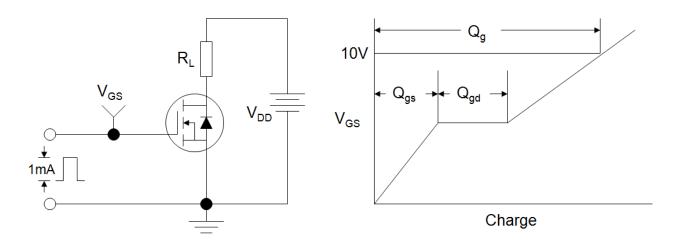


Figure B: Resistive Switching Test Circuit and Waveform

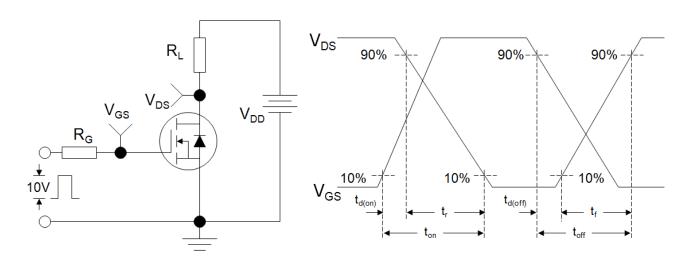
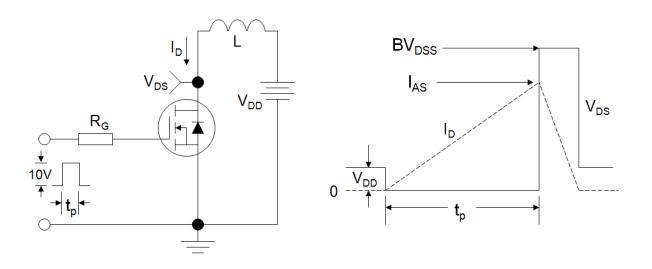
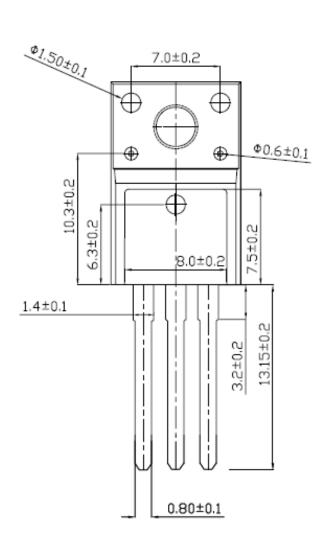


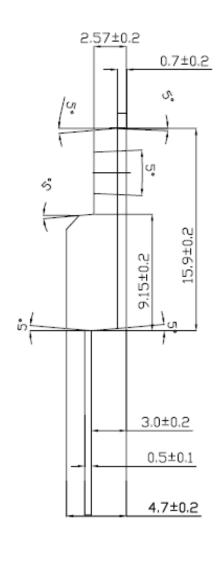
Figure C: Unclamped Inductive Switching Test Circuit and Waveform





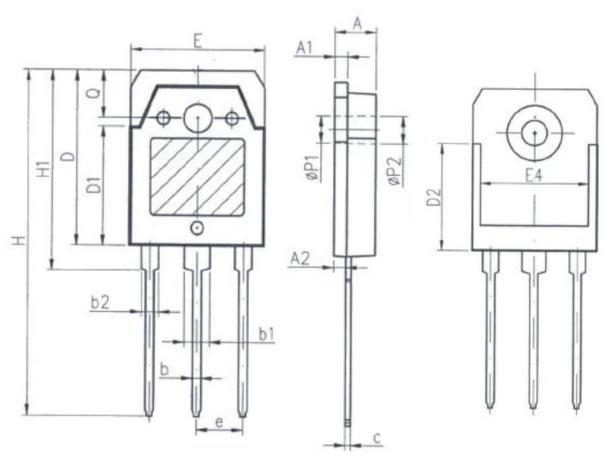
TO-220F





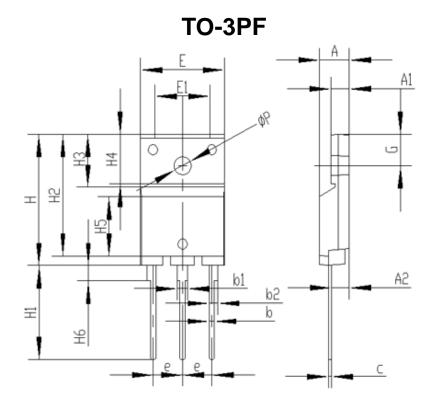


TO-3P



Unit:mm				
Symbol	Min.	Max.		
Α	4. 6	5		
A1	1. 4	1. 65		
A2	1. 18	1. 58		
b	0.8	1. 2		
b1	2. 8	3. 2		
b2	1.8	2. 2		
C	0.5	0. 75		
D	19. 6	20. 2		
D1	13. 55	14. 25		
D2	12. 9	PREF		
E	15. 35	15. 85		
E4	12. 6	_		
е	5. 45TYP			
Н	40. 1	40. 9		
H1	23. 15	23. 65		
P1	3. 2REF			
P2	3. 5REF			







Symbol		单位 mm	
Cymbol	Min	Nom	Max
Α	5. 30	5. 50	5. 70
A1	3. 30	3. 50	3. 70
A2	3. 20	3. 40	3.60
b	0.80	1.0	1. 20
b1	1.80	2.00	2. 20
b 2	1.40	1.60	1.80
С	0.40	0. 50	0.60
е	5. 25	5. 45	5. 65
E	15. 4	15. 6	15. 8
E1	10.0	10.2	10.4
Н	22.8	23. 0	23. 2
H1	16. 0	16. 5	17. 0
H2	21. 2	21. 4	21. 6
Н3	9. 10	9. 30	9.50
H4	8. 55	8. 75	8. 95
H5	10. 2	10.4	10.6
H6	2. 55	2. 70	2.85
G	5. 3	5. 5	5. 7
ΦР	3. 00	3. 20	3. 40

CS4N100F,CS4N100V,CS4N100VF

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